



Japan Physical Interfaces & Carriers Committee Meeting Summary and Minutes

Japan Standards Spring Meetings 2013
7th March 2013, 13:30 – 17:30
JPR 7F Conference Room1, SEMI Japan Office, Tokyo, Japan

Next Committee Meeting

6th June 2013, 13:30-17:30 Japan Standard Time JPR 7F Conference Room1, SEMI Japan Office, Tokyo, Japan

Committee Announcements (optional)

None

Table 1 Meeting Attendees

Co-Chairs: Tsuyoshi Nagashima (Miraial), Tsutomu Okabe (TDK)

SEMI Staff: Hirofumi Kanno

Company	Last	First	Company	Last	First
Acteon	Komatsu	Shoji	Muratec	Yamamoto	Makoto
Consultant	Kumai	Sadao	SUMCO	Nakai	Tetsuya
Consultant	Shimizu	Yasuhiro	Daifuku	Yamagata	Kenji
Tokyo Electron	Mashiro	Supika	Tokyo Electron	Kobayashi	Sensho
Dainichi Shoji	Ohyama	Koji	TDK	Okabe	Tsutomu
Sinfonia Technologie	Taniyama	Yasushi	Miraial	Nagashima	Tsuyoshi

Table 2 Leadership Changes

None

Table 3 Ballot Results (or move to Section 4, Ballot Review)

Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

Document #	Document Title	Committee Action
	New Standard: Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard	Passed as super clean

Table 4 Authorized Ballots (or move to Section 7, New Business)

None

Table 5 Authorized Activities (or move to Section 7, New Business)

None

Note: SNARFs and TFOFs are available for review on the SEMI Web site at:

 $\underline{http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF}$

Table 6 New Action Items (or move to Section 8, Action Item Review)

None





Table 7 Previous Meeting Actions Items (or move to Section 8, Action item Review)

None

1 Welcome, Reminders, and Introductions

Tsuyoshi Nagashima (Miraial) called the meeting to order at 13:30. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01, Required Elements Reg_20100302_E+J

2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

Motion: Approve the minutes of the previous meeting

By / 2nd: Tsutomu Okabe (TDK) / Kenji Yamagata (Daifuku)

Discussion: None **Vote:** 11:0

Attachment: 06, Required Elements Reg_20100302_E+J

3 Liaison Reports

3.1 Europe Equipment Automation > Committee

No update. The next Europe Equipment Automation committee meeting will take place on October 7-10, 2013 at Messe Dresden in Germany in conjunction with SEMICON Europa.

3.2 North America PIC Committee

No update. The next North America PIC Committee is scheduled for 3rd April, 2013 during North America Standards Spring meetings 2013.

3.3 SEMI Staff Report

Hirofumi Kannno (SEMI) gave the SEMI Staff Report. Of note:

- SEMI Global 2013 Calendar of Events
- NA Spring Meeting
- 2012 Critical Dates for SEMI Standards Ballots
- Publication Update
- New Standards Ballot and Membership Systems
- New Ballot Formatting Templates
- Style Manual and Compilation of Terms
- Contact Information

Attachment: 02, SEMI Staff Report 2013 March R0.3





4 Ballot Review

4.1 Document # 5488A, New Standard: Specification for 450 mm Cluster Module Interface: Mechanical Interface and Transport Standard

Tallies

	Return	Distribution Return Rate
Yellow	47	÷ 75 = 62.7% >=60%
Lilac & Others	21	
Total Vote	68	
Reject	0	
Accept	19	

NOTICE: This document met the 90% approval condition set forth in Section 9.6.3 of the *Regulations Governing SEMI Standards Committees* at the close of balloting.

NOTICE: This document did NOT meet the 90% approval condition set forth in Section 9.6.3 of the *Regulations Governing SEMI Standards Committees* at the close of balloting.

Rejects/Negatives

None

Comments

None

NOTICE: Items from "Reject" votes that are clearly marked by the voter as comments are included here.

Attachment: 03, Doc.4588A_Procedural Review Voting Sheet





5 Subcommittee & Task Force Reports

5.1 Global POIC Standards Maintenance Task Force

Shoji Komatsu (Acteon) reported that there was no activity in Japan.

5.2 450 mm International PIC Task Force

Shoji Komatsu (Acteon) reported for the 450 mm International PIC Task Force.

- EFEM Robot "Pocket" Volume Definition
 - The TF considers including the definition in SEMI E154.

Revised E154 document is on the Cycle2 now. The above action will be taken by the TF after published the document.

New AUX Information document will be submitted the North America PI&C committee for approval at the committee meeting in April 4.

Attachment: 04, 450mm IPIC TF meeting agenda rev1-20130305

5.3 International Process Module Physical Interface Task Force

Supika Mashiro reports that the TF considers taking next action after published the Doc.5488A.

5.4 450 mm AMHS Task Force

Kenji Yamagata reported the TF activity update.

- Signal tower standardization (TBD)
- SNARF to revise E156 is in preparation
 - > The SNARF will be submitted at the next North America PI&C committee meeting in April 4.
- 5.5 (Silicon Wafer Committee) JA Shipping Box Task Force / (JA Silicon Wafer Committee and NA PI&C Committee)Int'l 450mm Shipping Box Task Force

Yasuhiro Shimizu (Consultant) reported for the Task Force. This report contained information on 450 mm wafer shipping system.

Attachment: 05, SHIPPING BOX TF REPORT 2013_03_07

- 5.6 Updates from Polished /Epi/ASI/AWG (Int'l 450mm related TF) under the global Silicon Wafer Committee No report
- 5.7 Int'l Reticle SMIF Pod & Load Port Interoperability Task Force

Koji Ohyama (Dainichi Shoji) reported for the Task Force. This report contained information on RSP Sensor Zone (Door & Shell) – Related Information draft.





6 Old Business

6.1 Leadership Changes

Kenji Yamagata will be approved as a new co-chair of Japan PI&C Committee at the next JRSC meeting on April 19, 2013.

6.2 Summary Report for STEP 450 mm in Conjunction with SEMICON Japan 2012

Hirofumi Kanno (SEMI Staff) briefly reported the summary.

A SEMI Standards Technical Education Program (STEP) on 450 mm wafers was held on December 7 in Makuhari, in conjunction with SEMICON Japan 2012. This program aimed to give clear and detailed explanations about published 450 mm Standards. This also introduced the latest developments in 450 mm activities, including standardization of physical interfaces and other interoperability-related specifications for the 450 mm (vacuum) process modules and transfer modules of cluster tools, and standardization of load port for the tape frame cassettes for the 450 mm packaging process. It drew more than 60 participants.

7 New Business

None

8 Action Item Review

8.1 Open Action Items

None

8.2 New Action Items

None

9 Next Meeting and Adjournment

The next meeting of the Japan PIC committee is scheduled for 6th June, 2013 at SEMI Japan Office in Tokyo, Japan.





Respectfully submitted by: Hirofumi Kanno Manager, Standards SEMI Japan

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Minutes approved by:

Tsuyoshi Nagashima (Miraial), Co-chair	<date approved=""></date>
Tsutomu Okabe (TDK), Co-chair	<date approved=""></date>

Table 8 Index of Available Attachments #1

#	Title	#	Title
01	Required Elements Reg_20100302_E+J		
02	SEMI Staff Report 2013 March R0.3		
03	Doc.4588A_Procedural Review Voting Sheet		
04	04 450mm IPIC TF meeting agenda rev1-20130305		
05	05 SHIPPING BOX TF REPORT 2013_03_07		
06	PIC mins 121207_r03		

^{#1} Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.